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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (original): An RF module comprising;
a multi-layered substrate;
a base-band IC, a memory IC and an RF-IC mounted on said multi-layered substrate;
an RF passive component incorporated in said multi-layered substrate; and
a wiring pattern incorporated in said multi-layered substrate, said wiring pattern interconnecting said base-band IC and said memory IC.

Claim 2 (original): An RF module according to Claim 1, further comprising an antenna incorporated in said multi-layered substrate.

Claim 3 (original): An RF module according to Claim 1, wherein at least one of said base-band IC, said memory IC and said RF-IC is a bare chip.

Claim 4 (original): An RF module according to Claim 3, wherein at least one cavity is formed in a portion of said multi-layered substrate, and said bare chip is disposed in said at least one cavity.

Claim 5 (original): An RF module according to Claim 1, wherein said base-band IC and said memory IC are mounted on a first side of said multi-layered substrate, and said RF-IC is mounted on a second side of said multi-layered substrate.

Claim 6 (original): An RF module according to Claim 5, further comprising a shielding ground electrode pattern interposed between the first side of said multi-

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layered substrate on which said base-band IC and said memory IC are mounted and said RF passive component incorporated in said multi-layered substrate.

Claim 7 (original): An RF module according to Claim 1, further comprising at least one trimming electrode pattern disposed on a surface of said multi-layered substrate and arranged to enable adjustment of frequency characteristics of the RF module.

Claim 8 (original): An RF module according to Claim 4, wherein said RF-IC is a bare chip, said RF module further comprising:

a ground pattern arranged to prevent RF signal radiation provided within said multi-layered substrate at a location on the bottom surface of said bare chip, so as to prevent unnecessary radiation of RF signals from said RF-IC; and

a plurality of via holes arranged within said multi-layered substrate and around said bare chip, said via holes providing connection to said ground electrode pattern for preventing RF signal radiation.

Claim 9 (original): An RF module according to Claim 1, further comprising a metallic case disposed on said multi-layered substrate.

Claim 10 (original): An RF module according to Claim 9, wherein the metallic case is arranged to define a portion of an antenna.

Claim 11 (original): An RF module comprising;
a substrate;
a plurality of different electronic components mounted on said substrate;
an RF passive component incorporated in said substrate; and
a wiring pattern incorporated in said multi-layered substrate, said wiring pattern interconnecting at least two of said IC components.

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Claim 12 (original): An RF module according to Claim 11, wherein the substrate is a multi-layered substrate 12 made of ceramic material.

Claim 13 (original): An RF module according to Claim 11, wherein the plurality of electronic components include a base-band IC, a memory IC, a quartz oscillator and surface-mounted components.

Claim 14 (original): An RF module according to Claim 13, wherein the surface mounted components includes at least one of a chip-type inductor, a chip-type capacitor, a chip resistor, a chip-type transistor, and a chip-type diode.

Claim 15 (original): An RF module according to Claim 11, further comprising a metallic case disposed on said substrate.

Claim 16 (original): An RF module according to Claim 11, wherein the metallic case is arranged to define a portion of an antenna.

Claim 17 (original): An RF module according to Claim 11, wherein at least one cavity is formed in a portion of said substrate, and at least one RF-IC is disposed in said at least one cavity.

Claim 18 (original): An RF module according to Claim 11, further comprising an antenna incorporated in said substrate.

Claim 19 (original): An RF module according to Claim 13, wherein at least one of said base-band IC, said memory IC and said RF-IC is a bare chip.

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Claim 20 (original): An RF module according to Claim 19, wherein at least one cavity is formed in a portion of said substrate, and said bare chip is disposed in said at least one cavity.

Claim 21 (original): An RF module according to Claim 13, wherein said base-band IC and said memory IC are mounted on a first side of said substrate, and said RF-IC is mounted on a second side of said multi-layered substrate.

Claim 22 (original): An RF module according to Claim 21, further comprising a shielding ground electrode pattern interposed between the first side of said substrate on which said base-band IC and said memory IC are mounted and said RF passive component incorporated in said substrate.

Claim 23 (original): An RF module according to Claim 13, further comprising at least one trimming electrode pattern disposed on a surface of said substrate and arranged to enable adjustment of frequency characteristics of the RF module.

Claim 24 (original): An RF module according to Claim 23, wherein said RF-IC is a bare chip, said RF module further comprising:

- a ground pattern arranged to prevent RF signal radiation provided within said substrate at a location on the bottom surface of said bare chip, so as to prevent unnecessary radiation of RF signals from said RF-IC; and

- a plurality of via holes arranged within said substrate and around said bare chip, said via holes providing connection to said ground electrode pattern for preventing RF signal radiation.